



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN# 20200109000.1**

**Qualification of DMOS6 as an additional Wafer Fab Site option for select devices  
Change Notification / Sample Request**

**Date:** January 14, 2020  
**To:** PREMIER FARNELL PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team ([PCN\\_ww\\_admin\\_team@list.ti.com](mailto:PCN_ww_admin_team@list.ti.com)). For sample requests or sample related questions, contact your local Field Sales Representative.

PCN Team  
SC Business Services

**20200109000.1**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
CC2640R2FRGZT	null
CC2640R2FRHBT	null
CC2640R2FRSMT	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20200109000.1	<b>PCN Date:</b>	Jan 14, 2020
<b>Title:</b>	Qualification of DMOS6 as an additional Wafer Fab Site option for select devices in F021 Technology		
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Apr 14, 2020	<b>Estimated Sample Availability:</b>	Date provided at sample request.
<b>Change Type:</b>			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Assembly Materials	
<input type="checkbox"/> Design	<input type="checkbox"/> Electrical Specification	<input type="checkbox"/> Mechanical Specification	
<input type="checkbox"/> Test Site	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	
<input type="checkbox"/> Wafer Bump Site	<input type="checkbox"/> Wafer Bump Material	<input type="checkbox"/> Wafer Bump Process	
<input checked="" type="checkbox"/> Wafer Fab Site	<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Wafer Fab Process	
	<input type="checkbox"/> Part number change		

### PCN Details

#### Description of Change:

This change notification is to announce the addition of DMOS6 as an additional Wafer Fab site option for the products listed in the "Product Affected" section of this document.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
TSMC-F14	F021	300 mm	DMOS6	F65	300 mm

In support of the qualification of the DMOS6 Wafer Fab site, the flash design library was changed to allow production in the new fab site. The change does not impact device functionality, and device performance is accounted for in the respective datasheet specifications.

Qual details are provided in the Qual Data Section.

#### Reason for Change:

Continuity of Supply

#### Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

#### Changes to product identification resulting from this PCN:

##### Current

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
TSMC-F14	T14	TWN	Tainan City

##### New Fab Site

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
DMOS6	DM6	USA	Dallas

Sample product shipping label (not actual product label)

 <b>TEXAS INSTRUMENTS</b> MADE IN: Malaysia 2DC: 20: <table border="1"> <tr> <td>MSL '2 / 260C / 1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 / 235C / UNLIM</td> <td>03/29/04</td> </tr> </table> OPT: ITEM: 39 <b>LBL: 5A (L)T0:1750</b>	MSL '2 / 260C / 1 YEAR	SEAL DT	MSL 1 / 235C / UNLIM	03/29/04	 	(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483S12 (P) (2P) REV: (V) 0033317 (20L) CS0: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS
MSL '2 / 260C / 1 YEAR	SEAL DT					
MSL 1 / 235C / UNLIM	03/29/04					

**Product Affected Group:**

CC2640R2FRGZR	CC2640R2FRHBR	CC2640R2FRSMR	FRE014RGZR
CC2640R2FRGZT	CC2640R2FRHBT	CC2640R2FRSMT	FRE014RHBR

**Qualification Report**  
Approve Date 10-DEC-2019

**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: CC2640R2FRGZR	Qual Device: CC2640R2FRSMR	QBS Package Reference: CC2640R2FRGZR	QBS Package Reference: CC2640R2FRHBR	QBS Package Reference: CC2640R2FRSMR
HTOL	High Temp. Operating Life, 125C, 100K W/E cycle preconditioning	1000 Hours	3/231/0	-	-	-	-
HTSL	High Temp. Storage Bake, 150C, 100K W/E cycle preconditioning	1000 Hours	3/215/0	-	-	-	-
AC	Autoclave 121C	96 Hours	3/231/0	-	1/77/0	1/77/0	1/77/0
HAST	Biased HAST, 110C/85%RH	264 Hours	3/231/0	-	1/77/0	-	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	-	1/77/0	1/77/0	1/77/0
TC	Temperature Cycle, -55/125C	700 Cycles	3/231/0	1/77/0	1/77/0	1/77/0	1/77/0
CDM	ESD CDM	750 V	1/3/0	1/3/0	-	-	-
HBM	ESD HBM	2500 V	1/3/0	1/3/0	-	-	-
LU	Latch-up, High Temp	+/- 100 mA and 1.5 x Vmax @ max Tj	1/3/0	-	-	-	-

- QBS: Qualification By Similarity

- Qualification Devices CC2640R2FRGZR, CC2640R2FRHBR, and CC2640R2FRSMR are qualified at moisture sensitivity LEVEL3-260C.

- Preconditioning was performed for Autoclave, Biased HAST, Temperature Cycle, and HTSL.

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
WW PCN Team	<a href="mailto:PCN_ww_admin_team@list.ti.com">PCN_ww_admin_team@list.ti.com</a>

**IMPORTANT NOTICE AND DISCLAIMER**

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale ([www.ti.com/legal/termsofsale.html](http://www.ti.com/legal/termsofsale.html)) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision

of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.